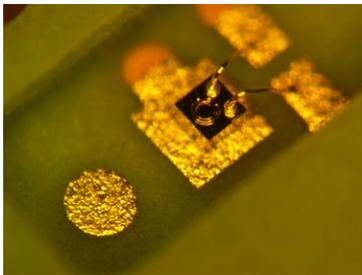
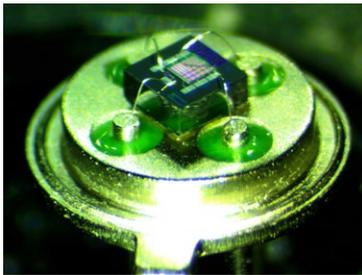


# Unlock Potential in Your Business



## Advanced microelectronics solutions

Increased demand for lower cost, technically advanced and smaller lightweight electronics has changed the electronics assembly landscape. For 25 years, Celestica has been a trusted partner to the world's leading companies in high reliability markets including Aerospace & Defense, Healthcare, Industrial, Automotive & Communications. We manufacture some of the most complex electronics in the world and bring deep expertise in microelectronics, providing customers with specialized capabilities in our clean room labs - from design and value engineering, testing to complex assembly.

### Our Services:

- High accuracy die bonding
- Epoxy dispensing or daubing
- Flip chip with flux dipping
- Wirebonding: Ball, Wedge, Ribbon, Gold or Aluminum Wire
- Plasma cleaning
- Die encapsulation
- Pull test, die and ball shear

### Applications / Technology

- Sensors
- Optoelectronics
- MEMS (sensing and actuators)
- LIDAR
- Chip on Board (COB)
- First level packaging
- Flip Chip

# We imagine, develop and deliver a better future with our customers.

## The right partner can make all the difference.

**Our customized microelectronics solutions support the success of your program with:**

- Newly designed ISO class 6 microelectronics clean room lab in North America
- Dedicated & experienced team for project management & consulting
- Innovative solutions that help you achieve product miniaturization
- Improved performance for high-reliability mission-critical applications
- Automation capabilities to optimize efficiency, reduce cost and improve time-to-market
- Processes in place that meet the most stringent standards



## We engineer solutions.

Leveraging over 25 years of manufacturing experience and a 75 year OEM heritage, we offer state-of-the-art:

- Microelectronics assembly in an ISO class 6 cleanroom
- SMT assembly for complex assemblies
- PTH assembly with wave solder and selective solder
- High-level electro-mechanical system assembly and integration
- Advanced automation solutions
- Underfill and conformal coating
- AOI, API, X-ray
- ICT, flying probe and functional test
- Material science and failure analysis lab
- Reliability testing



## Trusted End-to-End Product Lifecycle Solutions Provider

Design &  
Engineering

Test &  
Validation

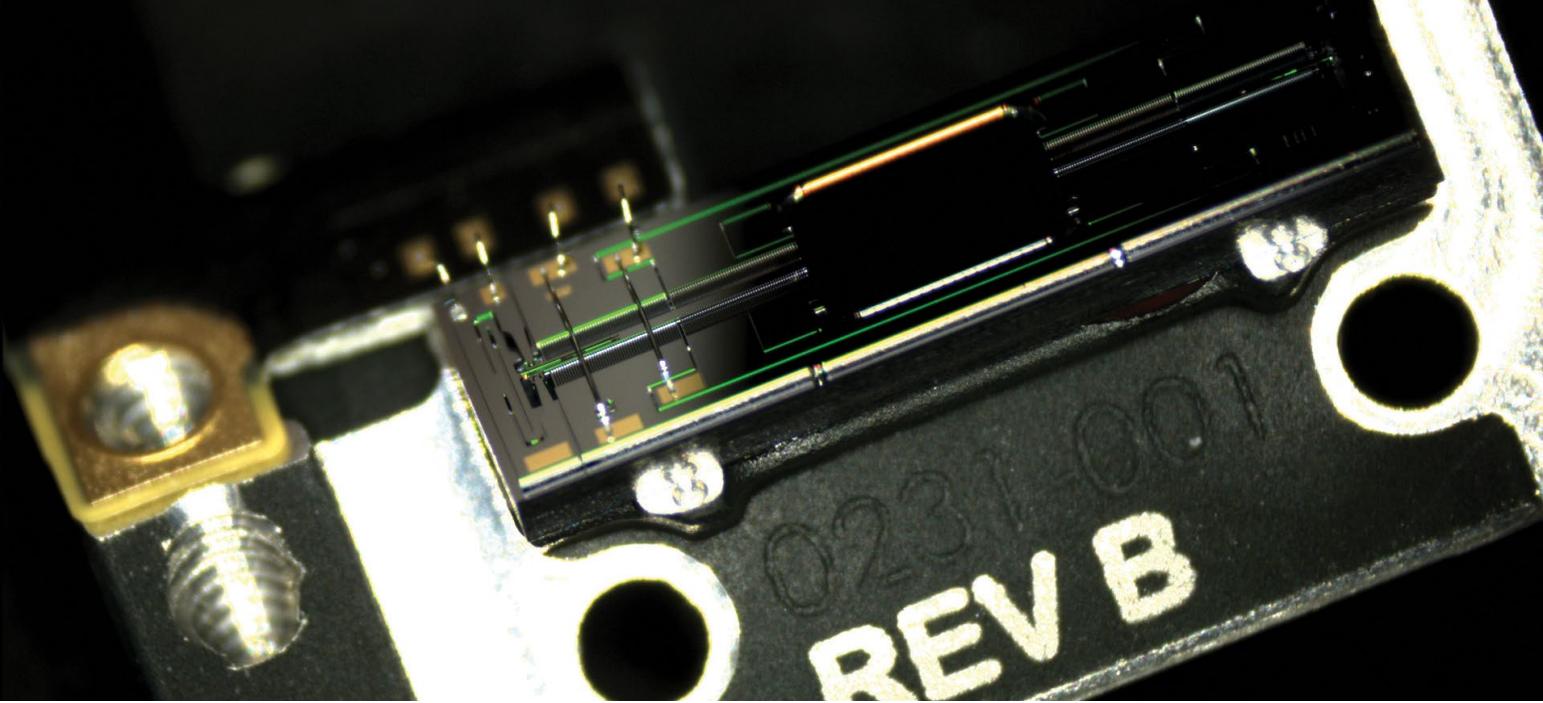
Build

Spares &  
Repairs

Lifecycle  
Management

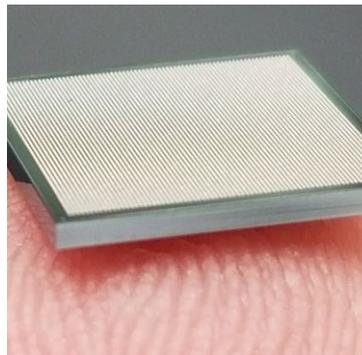
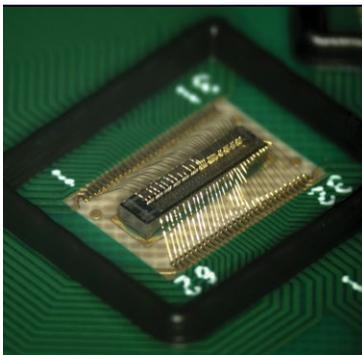
Services &  
Solutions

Engineering Services Delivers Value Throughout the Lifecycle



## Single source solution enabling your success every step of the way

Throughout aggressive new product introduction or redesign, we work as a seamless extension of your team to provide a broad range of high-value solutions that are easily integrated into the manufacturing and test process, helping you reduce costs and improve time-to-market.



## Our Certifications:

- ANSI S20.20
- ISO 9001
- ISO 14001, OHSAS 18001
- ISO 13485
- AS 9100
- TL 9000
- CGP / ITAR / EAR
- C-TPAT / PIP
- Nadcap - Electronics CCA, CHA
- IPC standards compliance

### For enquiries please contact:

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